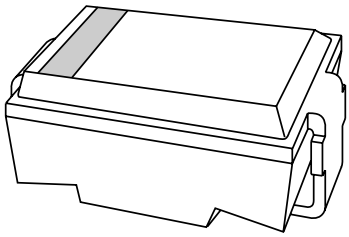
DATA SHEET



BZG04 series
Transient voltage suppressor diodes

Product specification
Supersedes data of 1996 Sep 19

2002 Jul 04

Philips
Semiconductors

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Transient voltage suppressor diodes BZG04 series

FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- UL 94V-O classified plastic package
- Transient suppressor stand-off voltage range:
  8.2 to 220 V for 32 types
- Shipped in 12 mm embossed tape.

DESCRIPTION

DO-214AC surface mountable package with glass passivated chip.

The well-defined void-free case is of a transfer-moulded thermo-setting plastic.

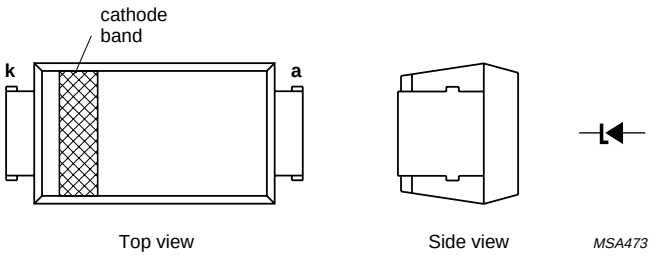


Fig.1 Simplified outline (DO-214AC; SOD106) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
P_{RSM}	non-repetitive peak reverse power dissipation	10/1000 μs exponential pulse (see Fig.4); T_j = 25 °C prior to surge; see also Fig.2	–	300	W
T_{stg}	storage temperature		–65	+175	°C
T_j	junction temperature		–65	+175	°C

ELECTRICAL CHARACTERISTICS

Total series

T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_F	forward voltage	I_F = 0.5 A; see Fig.3	–	1.2	V

Per type

T_j = 25 °C unless otherwise specified.

TYPE NUMBER	REVERSE BREAKDOWN VOLTAGE	TEMPERATURE COEFFICIENT		TEST CURRENT	CLAMPING VOLTAGE		REVERSE CURRENT at STAND-OFF VOLTAGE	
	$V_{(BR)R}$ (V) at I_{test}	S_Z (%/K) at I_{test}		I_{test} (mA)	$V_{(CL)R}$ (V)	at I_{RSM} (A) note 1	I_R (μA)	at V_R (V)
	MIN.	MIN.	MAX.		MAX.		MAX.	
BZG04-8V2	9.4	0.05	0.09	50	14.8	20.3	20	8.2
BZG04-9V1	10.4	0.05	0.10	50	15.7	19.1	5	9.1
BZG04-10	11.4	0.05	0.10	50	17.0	17.7	5	10
BZG04-11	12.4	0.05	0.10	50	18.9	15.9	5	11
BZG04-12	13.8	0.05	0.10	50	20.9	14.4	5	12
BZG04-13	15.3	0.06	0.11	25	22.9	13.1	5	13
BZG04-15	16.8	0.06	0.11	25	25.6	11.7	5	15
BZG04-16	18.8	0.06	0.11	25	28.4	10.6	5	16
BZG04-18	20.8	0.06	0.11	25	31.0	9.7	5	18
BZG04-20	22.8	0.06	0.11	25	33.8	8.9	5	20
BZG04-22	25.1	0.06	0.11	25	38.1	7.9	5	22
BZG04-24	28	0.06	0.11	25	42.2	7.1	5	24
BZG04-27	31	0.06	0.11	25	46.2	6.5	5	27
BZG04-30	34	0.06	0.11	10	50.1	6.0	5	30
BZG04-33	37	0.06	0.11	10	54.1	5.5	5	33
BZG04-36	40	0.07	0.12	10	60.7	4.9	5	36
BZG04-39	44	0.07	0.12	10	65.5	4.6	5	39
BZG04-43	48	0.07	0.12	10	70.8	4.2	5	43
BZG04-47	52	0.07	0.12	10	78.6	3.8	5	47
BZG04-51	58	0.08	0.13	10	86.5	3.5	5	51
BZG04-56	64	0.08	0.13	10	94.4	3.2	5	56
BZG04-62	70	0.08	0.13	10	103.5	2.9	5	62
BZG04-68	77	0.08	0.13	10	114	2.6	5	68
BZG04-75	85	0.09	0.13	5	126	2.4	5	75
BZG04-82	94	0.09	0.13	5	139	2.2	5	82
BZG04-91	104	0.09	0.13	5	152	2.0	5	91
BZG04-100	114	0.09	0.13	5	167	1.8	5	100
BZG04-110	124	0.09	0.13	5	185	1.6	5	110
BZG04-120	138	0.09	0.13	5	204	1.5	5	120
BZG04-130	153	0.09	0.13	5	224	1.3	5	130

TYPE NUMBER	REVERSE BREAKDOWN VOLTAGE	TEMPERATURE COEFFICIENT		TEST CURRENT	CLAMPING VOLTAGE		REVERSE CURRENT at STAND-OFF VOLTAGE	
	$V_{(BR)R}$ (V) at I_{test}	S_Z (%/K) at I_{test}		I_{test} (mA)	$V_{(CL)R}$ (V)	at I_{RSM} (A) note 1	I_R (μA)	at V_R (V)
	MIN.	MIN.	MAX.		MAX.		MAX.	
BZG04-150	168	0.09	0.13	5	249	1.2	5	150
BZG04-160	188	0.09	0.13	5	276	1.1	5	160
BZG04-180	208	0.09	0.13	2	305	1.0	5	180
BZG04-200	228	0.09	0.13	2	336	0.9	5	200
BZG04-220	251	0.09	0.13	2	380	0.8	5	220

Note

1. Non-repetitive peak reverse current in accordance with *"IEC 60-1, Section 8"* (10/1000 μs pulse); see Fig.4.

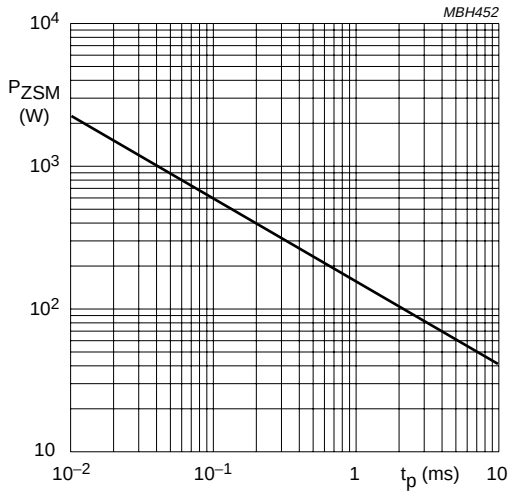
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}tp}$	thermal resistance from junction to tie-point		25	K/W
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient	note 1	100	K/W
		note 2	150	K/W

Notes

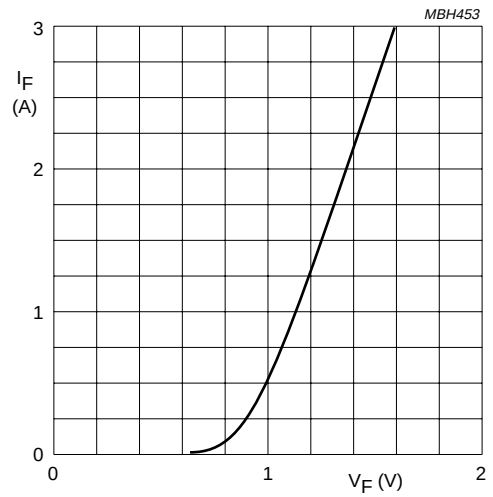
1. Device mounted on an Al_2O_3 printed-circuit board, 0.7 mm thick; thickness of Cu-layer ≥35 μm, see Fig.5.
2. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.5. For more information please refer to the *"General Part of associated Handbook"*.

GRAPHICAL DATA



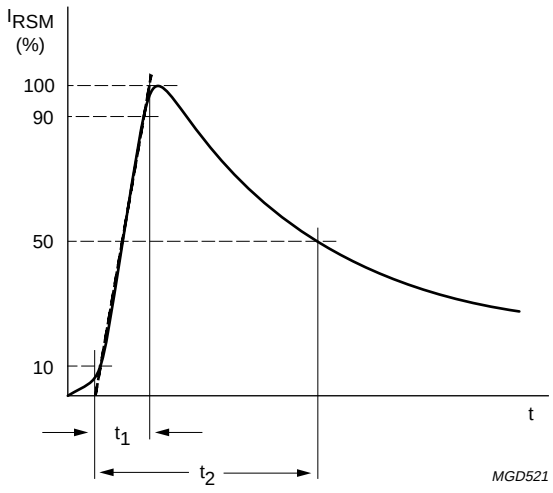
T_j = 25 °C prior to surge.

Fig.2 Maximum non-repetitive peak reverse power dissipation as a function of pulse duration (square pulse).



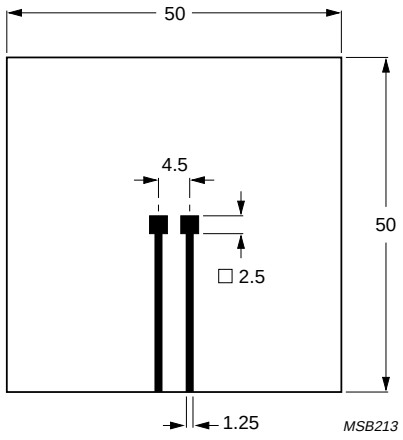
T_j = 25 °C.

Fig.3 Forward current as a function of forward voltage; typical values.



In accordance with *"IEC 60-1, Section 8"*.
t_1 = 10 µs.
t_2 = 1000 µs.

Fig.4 Non-repetitive peak reverse current pulse definition.

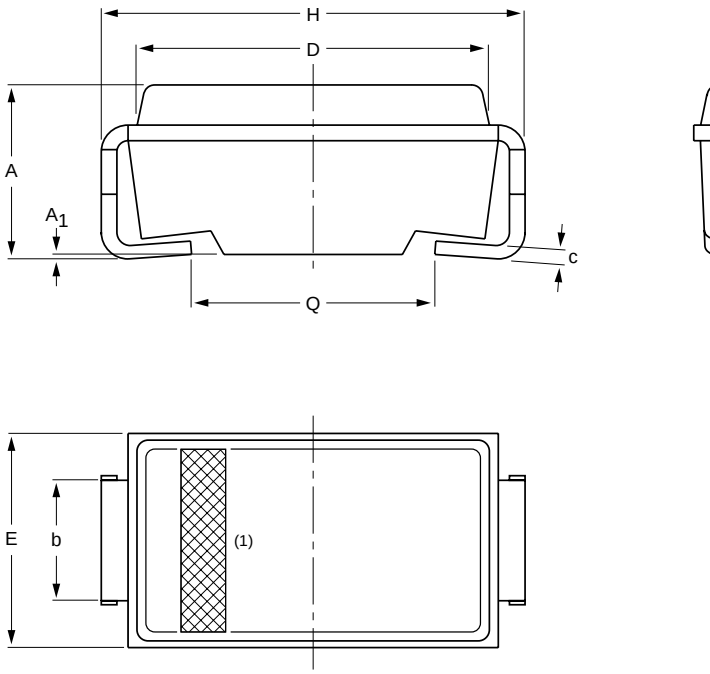


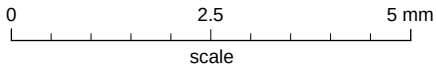
Dimensions in mm.

Fig.5 Printed-circuit board for surface mounting.

PACKAGE OUTLINE

Transfer-moulded thermo-setting plastic small rectangular surface mounted package; 2 connectors **SOD106**





DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	c	D	E	H	Q
mm	2.3 2.0	0.05	1.6 1.4	0.2	4.5 4.3	2.8 2.4	5.5 5.1	3.3 2.7

Note

1. The marking band indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOD106		DO-214AC				97-06-09

DATA SHEET STATUS

DATA SHEET STATUS[1]	PRODUCT STATUS[2]	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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